

January 4, 2001

To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

Subject:

Divisional Patent Application of
Serial No.: 09/442,497 11/18/99

SHENG-HSIUNG CHEN

METHOD OF IMPROVING COPPER PAD ADHESION

PRELIMINARY AMENDMENT

Dear Sir:

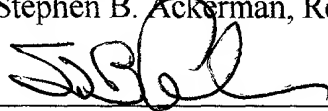
This is a preliminary amendment for the above referenced Divisional Patent Application. Please amend the above identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on January 4, 2001.

Stephen B. Ackerman, Reg. No. 37,761

Signature/Date



1/4/01

097555993-040304

PLEASE AMEND THE SPECIFICATION AS FOLLOWS:

After the title, insert -- This is a division of Patent Application serial number 09/442,497, filing date 11/18/99, Method Of Improving Copper Pad Adhesion, assigned to the same assignee as the present invention.

REMARKS

A reference to the parent case has been added by Preliminary Amendment to this Divisional Patent Application.

The application is believed to be in condition for allowance. Allowance of the subject Patent Application is therefore respectfully requested.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'SBA', followed by a horizontal line extending to the right.

STEPHEN B. ACKERMAN, REG. NO. 37,761